

REMARKS

Claims 1-10, 12-19, 21 and 22 are pending. By this Amendment, the specification is amended to correct an informality.

The attached Appendix includes marked-up copies of each rewritten paragraph (37 C.F.R. §1.121(b)(1)(iii)).

I. The Claims Define Patentable Subject Matter

The Office Action rejects claims 1, 3-10, 12, 14-19, 21 and 22 under 35 U.S.C. §103(a) over U.S. Patent 5,677,575 to Maeta et al. (hereinafter "Maeta") in view of U.S. Patent 5,519,576 to Moore. This rejection is respectfully traversed.

Neither Maeta nor Moore disclose a film that is formed with a lower adhesion to an adhesive than a base material of a substrate as recited in independent claims 1 and 12. On page 3, the Office Action merely asserts that the film 1A is formed with a lower adhesion to the adhesive and a base material of the substrate. However, the Office Action provides no support for this argument. Applicant respectfully requests that the specific citation to this disclosure be made so that Applicant can properly respond to this argument.

The Office Action recognizes that Maeta does not disclose the film being broader than each of the leads at their portions opposed to the electrodes. Applicant respectfully disagrees that Moore provides this feature. In the invention of claims 1 and 12, each of the leads has its portion opposed to one of the electrodes. In Moore, wires 16 are used for electrical connection between the IC 21 and leads 40. The electrodes of the IC 21 are never opposed to the leads 40.

Furthermore, Moore discloses a metallic lead frame paddle on which the IC is mounted. See col. 1, lines 18-22. The lead frame consists of a metallicity framed paddle 36 on which the IC is mounted and lead fingers 50 are provided for electrically conductive paths from the bonding pads of the IC to external elements, such as circuit boards. See, e.g., Fig. 4

and col. 1 lines 15-22. Thus, Moore does not disclose a film as provided in the invention of claims 1 and 12.

The Office Action rejects claims 1-10, 12-19 and 22 under 35 U.S.C. §103(a) over U.S. Patent 5,804,882 to Tsukagoshi et al. (hereinafter "Tsukagoshi ") in view of Moore. This rejection is respectfully traversed.

Tsukagoshi does not disclose a film formed with a lower adhesion to an adhesive than a base material of a substrate as recited in independent claims 1 and 12. On page 5 of the Office Action, again it is merely asserted that Tsukagoshi discloses this feature, at Fig. 1. However, Fig. 1 is devoid of this feature. Again Applicant respectfully requests that specific disclosure of this feature be cited so that Applicant can properly respond to this argument.

The Office Action recognizes that Tsukagoshi does not disclose the film being broader than each of the leads at their portions opposed to the electrodes. As previously discussed, Moore does not provide this feature.

The Office Action rejects claims 2 and 13 under 35 U.S.C. §103(a) over Maeta and Moore and further in view of JP-07169795 to Oda. This rejection is respectfully traversed.

As previously discussed, claims 1 and 12 define patentable subject matter. Claims 2 and 13 depend from claims 1 and 12 respectively. Therefore, claims 2 and 13 also define patentable subject matter.

I. Conclusion

In view of the foregoing, Applicant respectfully submits that this application is in condition for allowance. Favorable consideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,



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Attachment:
Appendix

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<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>
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APPENDIX

Changes to Specification:

Page 16, lines 7-15:

This embodiment is constructed as described above, and the method of manufacture thereof is now described. First, on the base material of the substrate 10, the leads 12 and film 14 are formed. The leads 12 and film 14 can be formed in a separate processes, but are ~~preferable~~preferably formed in the same process. For example, a conductive foil such as a metal foil can be formed on the base material of the substrate 10, and this can be etched to form the leads 12 and film 14 together.